

Indianapolis, IN, USA - 12 September 2019

Name	Employer	Affiliation
Abbott, John	Corning Incorporated	Corning Incorporated
Anslow, Peter	Ciena	Ciena
Araki, Nobuyasu	Yazaki Corporation	YAZAKI
Bhatt, Vipul	Finisar Corporation	Finisar Corporation
bordogna, mark		Intel
Boyer, Rich	Aptiv - Signal and Power	Aptiv Signal and Power Solutions
Brandt, David	Rockwell Automation	Rockwell Automation
Braun, Ralf-Peter	Deutsche Telekom AG	Deutsche Telekom AG
Brillhart, Theodore	Fluke Corporation	Fluke Corporation
Brown, Blake		University of New Hampshire
Chalupsky, David	Intel Corporation	Intel Corporation
Chen, Chan	Applied Optoelectronics, Inc.	Applied Optoelectronics, Inc.
Choudhury, Golam	OFS	OFS
D'Ambrosia, John	Futurewei Technologies	Futurewei (U.S. Subsidiary of
Dawe, Piers J G	Mellanox Technologies	Mellanox Technologies
Dawson, Fred	Chemours Canada Company	Chemours Canada Company
DeSanti, Claudio	Google	Google
Donahue, Curtis	University of New Hampshire	UNH-IOL
Dudek, Michael	Marvell	Marvell
Estes, David	Spirent Communications	Spirent Communications
Ewen, John	Avera Semiconductor	Avera Semiconductor
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Franchuk, Brian	Emerson Automation Solutions	Emerson Automation Solutions
Fritsche, Matthias	HARTING Technologie Gruppe	HARTING Electronics GmbH
Goergen, Joel	Cisco Systems, Inc.	Cisco Systems, Inc.
Gore, Brandon	Samtec, Inc.	Samtec, Inc.
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Graber, Steffen	Pepperl+Fuchs AG	Pepperl+Fuchs AG
Grow, Robert	RMG Consulting	RMG Consulting
Gubow, Martin	Keysight Technologies	Keysight Technologies
Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Hajduczenia, Marek	Charter Communications	Charter Communications
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	Intel Corporation	Intel Corporation
HYAKUTAKE, YASUHIRO	Adamant Namiki Precision Jewel	Adamant Namiki Precision Jewel
Ito, Hiroaki	Yazaki Corporation	Yazaki Corporation
Jackson, Kenneth	Sumitomo Electric Device	Sumitomo Electric Industries, LTD
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.
Knittle, Curtis	Cable Television Laboratories Inc.	Cable Television Laboratories Inc.
Kolesar, Paul	CME Consulting	CommScope, Inc.
Kondo, Taiji	MegaChips Corporation	MegaChips Corporation
Kramer, Glen	Broadcom Corporation	Broadcom Corporation
Laubach, Mark	Broadcom Corporation	Broadcom Corporation

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Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Levin, Alex	Microsoft Corporation	Microsoft Corporation
Lewis, Jon	Dell EMC	Dell EMC
Lusted, Kent	Intel Corporation	Intel Corporation
Maguire, Valerie	The Siemon Company	The Siemon Company
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.
McIntosh, James	Microchip Technology, Inc.	Microchip Technology, Inc.
McMillan, Larry	Western Digital Corporation	Western Digital Corporation
McSorley, Gregory	Amphenol Corporation	Amphenol Corporation
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Mueller, Harald	Endress + Hauser	Endress + Hauser
Nadolny, James	Samtec, Inc.	Samtec
Nicholl, Shawn	Xilinx	Xilinx
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
Palkert, Thomas	EIC	Molex-Macom
Perez De Aranda Alonso, Ru	Knowledge Development for POF	KDPOF
Pham, Phong	US Conec, Ltd.	US Conec, Ltd.
Pittala, Fabio	Huawei Technologies	Huawei Technologies
Powell, William	Nokia	Nokia
Pozzebon, Dino	Microchip Technology, Inc.	Microchip Technology, Inc.
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Sayre, Edward	Samtec, Inc.	Teraspeed, a division of Samtec
Sedio, Stephen	TDK Corporation	TDK Corporation
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
Shrikhande, Kapil	Innovium Inc.	Innovium
Shuai, Jialong	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
Slavick, Jeff	Broadcom Inc	Broadcom
Sommers, Scott	Molex Incorporated	Molex Incorporated
Sparrowhawk, Bryan	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Stassar, Peter	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
Stewart, Heath	Analog Devices Inc.	Analog Devices Inc.
Swanson, Steven	Corning Incorporated	Corning Incorporated
Takayama, Kazuya	Nitto Denko Corporation	Nitto Denko Corporation
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT
Tracy, Nathan	TE Connectivity	TE Connectivity
Tremblay, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Trowbridge, Stephen	Nokia	Nokia
Tse, Richard	Microchip Technology, Inc.	Microchip Technology, Inc.
Vanderlaan, Paul	UL LLC	UL LLC

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Name	Employer	Affiliation
Wienckowski, Natalie	General Motors Company	General Motors Company
Wucher, Markus	Endress + Hauser Flowtec AG	Endress + Hauser
Zhang, Xingxin	Huawei Technologies Co. Ltd	Huawei Technologies Co., Ltd
Zhuang, Yan	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
Zimmerman, George	CME Consulting	CME Consulting/ADI, APL Group, Aquantia, BMW, CommScope, Inc., Cisco Systems, and SenTekse